MOSFET, N-Channel, POWERTRENCH®

100 V, 60 A, 8 mΩ

General Description

This N-Channel MOSFET is produced using ON Semiconductor's advanced POWERTRENCH® process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

Features

- Max $r_{DS(on)} = 8 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 13 \text{ A}$
- Max $r_{DS(on)} = 13.5 \text{ m}\Omega$ at $V_{GS} = 6 \text{ V}$, $I_D = 9.5 \text{ A}$
- Advanced Package and Silicon combination for low r_{DS(on)} and high efficiency
- MSL1 robust package design
- 100% UIL tested
- 100% Rg tested
- These Devices are Pb-Free and are RoHS Compliant

Applications

• DC-DC Conversion

MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

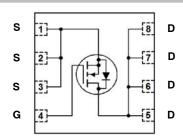
Symbol	Parameter	Value	Unit
V _{DS}	Drain to Source Voltage	100	٧
V _{GS}	Gate to Source Voltage	±20	٧
I _D	Drain Current: Continuous, T _C = 25°C Continuous, T _A = 25°C (Note 1a) Pulsed	60 12.4 200	Α
E _{AS}	Single Pulse Avalanche Energy (Note 3)	173	mJ
P _D	Power Dissipation: T _C = 25°C T _A = 25°C (Note 1a)	104 2.5	W
T _J , T _{STG}	Operating and Storage Junction Temperature Range	–55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

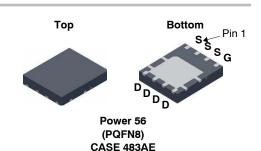


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N-Channel MOSFET



MARKING DIAGRAM



\$Y	= ON Semiconductor Logo
&Z	= Assembly Plant Code
&3	= Data Code (Year & Week)
01/	l et

&K = Lot

FDMS86101 = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Package	Quantity
FDMS86101	FDMS86101	Power 56 (PQFN8) (Pb-Free / Halogen Free)	3000/Tape&Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case	1.2	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
OFF CHARA	CTERISTICS		•		•	•
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V
$\Delta BV_{DSS} / \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25°C		66		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V			800	nA
I _{GSS}	Gate to Source Leakage Current, Forward	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA
ON CHARAC	CTERISTICS					
V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2.0	2.9	4.0	V
$\Delta V_{GS(th)} / \Delta T_J$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25°C		-9		mV/°C
r _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 13 A		6.3	8	mΩ
		V _{GS} = 6 V, I _D = 9.5 A		8.4	13.5	
		$V_{GS} = 10 \text{ V}, I_D = 13 \text{ A}, T_J = 125^{\circ}\text{C}$		10.9	14	
9FS	Forward Transconductance	V _{DS} = 10 V, I _D = 13 A		45		S
YNAMIC C	HARACTERISTICS					
C _{iss}	Input Capacitance	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz		2255	3000	pF
C _{oss}	Output Capacitance			460	610	pF
C _{rss}	Reverse Transfer Capacitance			30	45	pF
R_g	Gate Resistance		0.1	1.0	3.0	Ω
WITCHING	CHARACTERISTICS					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 50 \text{ V}, I_D = 13 \text{ A}, V_{GS} = 10 \text{ V},$		15	27	ns
t _r	Rise Time	$R_{GEN} = 6 \Omega$		11	20	ns
t _{d(off)}	Turn-Off Delay Time			27	44	ns
t _f	Fall Time			7	13	ns
Qg	Total Gate Charge	V_{GS} = 0 V to 10 V, V_{DD} = 50 V, I_D = 13 A		39	55	nC
		V_{GS} = 0 V to 5 V, V_{DD} = 50 V, I_D = 13 A		22	31	nC
Q _{gs}	Gate to Source Charge	V _{DD} = 40 V, I _D = 68 A		9.5		nC
Q _{gd}	Gate to Drain "Miller" Charge	V _{DD} = 40 V, I _D = 68 A		10.8		nC

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted) (continued)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit	
DRAIN-SOU	DRAIN-SOURCE DIODE CHARACTERISTICS						
V _{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _S = 2.1 A (Note 2)		0.7	1.2	V	
		V _{GS} = 0 V, I _S = 13 A (Note 2)		0.8	1.3		
t _{rr}	Reverse Recovery Time	I _F = 13 A, di/dt = 100 A/μs		56	90	ns	
Q _{rr}	Reverse Recovery Charge			61	98	nC	

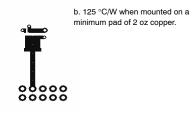
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

 R_{0,JA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0CA} is determined by the user's board design.

NOTES:



a. 50 °C/W when mounted on a
 1 in² pad of 2 oz copper.



- 2. Pulse Test: Pulse Width < 300 μ s, Duty cycle < 2.0%.
- 3. E_{AS} of 173 mJ is based on starting T_J = 25°C, L = 0.3 mH, I_{AS} = 34 A, V_{DD} = 75 V, V_{GS} = 10 V. 100% test at L = 0.1 mH, I_{AS} = 49 A.

TYPICAL CHARACTERISTICS

(T_J = 25°C unless otherwise noted)

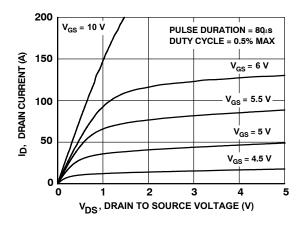


Figure 1. On Region Characteristics

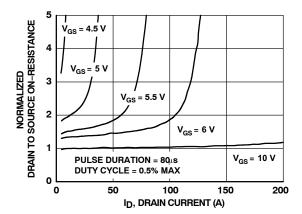


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

TYPICAL CHARACTERISTICS (continued)

(T_J = 25°C unless otherwise noted)

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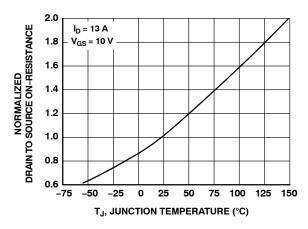


Figure 3. Normalized On Resistance vs. Junction Temperature

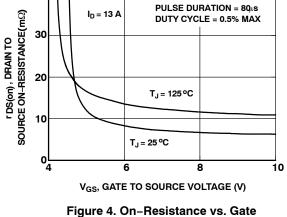


Figure 4. On-Resistance vs. Gate to Source Voltage

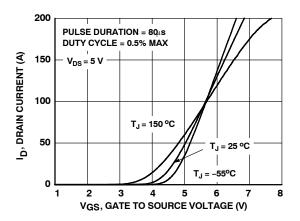


Figure 5. Transfer Characteristics

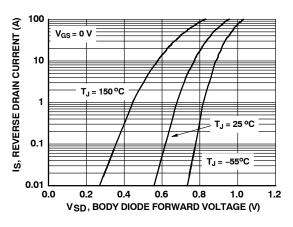


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

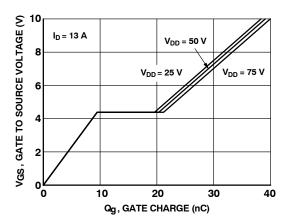


Figure 7. Gate Charge Characteristics

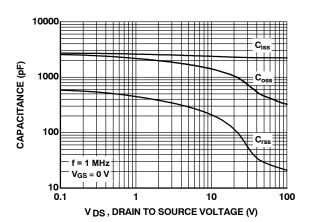


Figure 8. Capacitance vs. Drain to Source Voltage

TYPICAL CHARACTERISTICS (continued)

 $(T_J = 25^{\circ}C \text{ unless otherwise noted})$

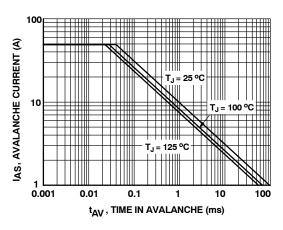


Figure 9. Unclamped Inductive Switching Capability

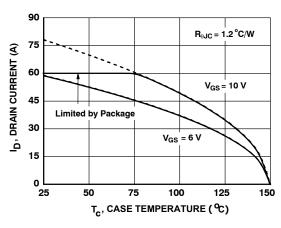


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

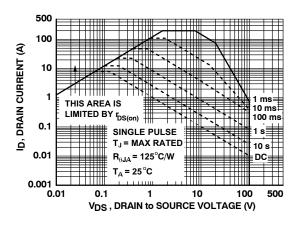


Figure 11. Forward Bias Safe Operating Area

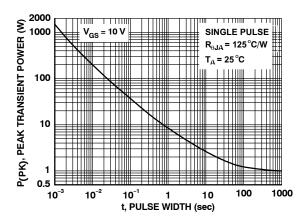


Figure 12. Single Pulse Maximum Power Dissipation

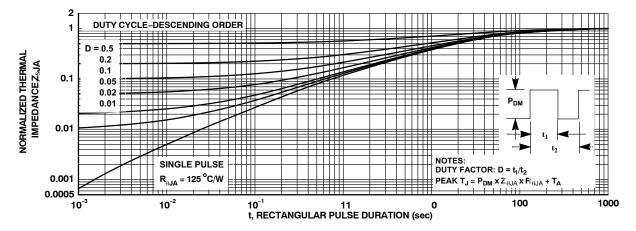
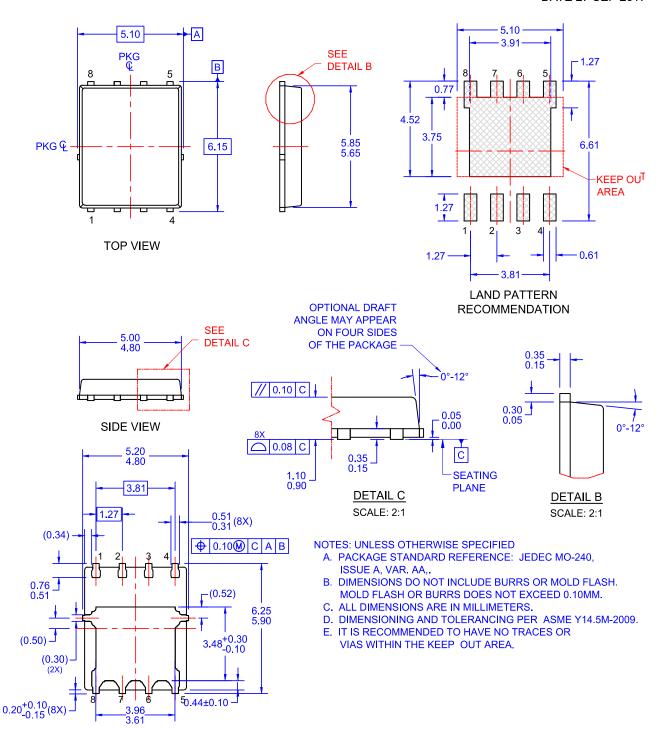


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

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